# **BUK9508-55A**

TrenchMOS™ logic level FET

22 March 2017

**Product data sheet** 

### 1. Description

N-channel enhancement mode field-effect power transistor in a plastic package using TrenchMOS<sup>™</sup> technology, featuring very low on-state resistance.

#### 2. Features

- TrenchMOS<sup>™</sup> technology
- Q101 compliant
- 175 °C rated
- Logic level compatible.

# 3. Applications

- Automotive and general purpose power switching:
  - ◆ 12 V and 24 V loads
  - Motors, lamps and solenoids.

### 4. Pinning information

Table 1: Pinning - SOT78, simplified outline and symbol

Pin	Description	Simplified outline	Symbol		
1	gate (g)	mb			
2	drain (d)	∑			
3	source (s)		ه الجام		
mb	mounting base; connected to drain (d)	1 2 3	MBB076 S		
		SOT78A (TO-220AB)			



#### 5. Quick reference data

Table 2: Quick reference data

Symbol	Parameter	Conditions	Тур	Max	Unit
$V_{DS}$	drain-source voltage (DC)		-	55	V
$I_D$	drain current (DC)	$T_{mb}$ = 25 °C; $V_{GS}$ = 5 V	-	125	Α
$P_{tot}$	total power dissipation	T <sub>mb</sub> = 25 °C	-	253	W
Tj	junction temperature		-	175	°C
$R_{DSon}$	drain-source on-state resistance	$T_j$ = 25 °C; $V_{GS}$ = 5 V; $I_D$ = 25 A	6.8	8	$m\Omega$
		$T_j$ = 25 °C; $V_{GS}$ = 4.5 V; $I_D$ = 25 A	-	8.5	$m\Omega$
		$T_j$ = 25 °C; $V_{GS}$ = 10 V; $I_D$ = 25 A	6.4	7.5	mΩ

# 6. Limiting values

Table 3: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	ı	Min	Max	Unit
$V_{DS}$	drain-source voltage (DC)		-		55	V
$V_{DGR}$	drain-gate voltage (DC)	$R_{GS} = 20 \text{ k}\Omega$	-	•	55	V
$V_{GS}$	gate-source voltage (DC)		-	•	±15	V
I <sub>D</sub>	drain current (DC)	$T_{mb} = 25  ^{\circ}C;  V_{GS} = 5  V;$	[1]	•	125	Α
		Figure 2 and 3	[2]	•	75	Α
		$T_{mb} = 100  ^{\circ}\text{C};  V_{GS} = 5  \text{V};  \text{Figure 2}$	[2]	•	75	Α
I <sub>DM</sub>	peak drain current	$T_{mb}$ = 25 °C; pulsed; $t_p \le 10 \mu s$ ; Figure 3	-	•	503	Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; Figure 1	-	•	253	W
T <sub>stg</sub>	storage temperature		-	-55	+175	°C
Tj	junction temperature		_	-55	+175	°C
Source-d	drain diode					
I <sub>DR</sub>	reverse drain current (DC)	T <sub>mb</sub> = 25 °C	[1]		125	Α
			[2]		75	Α
I <sub>DRM</sub>	peak reverse drain current	$T_{mb}$ = 25 °C; pulsed; $t_p \le 10 \mu s$	-	•	503	Α
Avalanch	ne ruggedness					
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	unclamped inductive load; $I_D$ = 75 A; $V_{DS} \le$ 55 V; $V_{GS}$ = 5 V; $R_{GS}$ = 50 $\Omega$ ; starting $T_{mb}$ = 25 °C	-	•	670	mJ

<sup>[1]</sup> Current is limited by power dissipation chip rating

<sup>[2]</sup> Continuous current is limited by package.

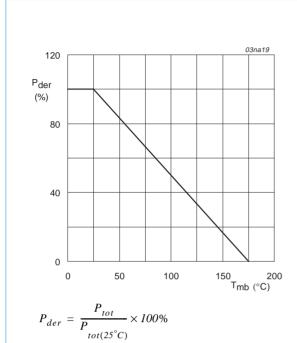


Fig 1. Normalized total power dissipation as a function of mounting base temperature.

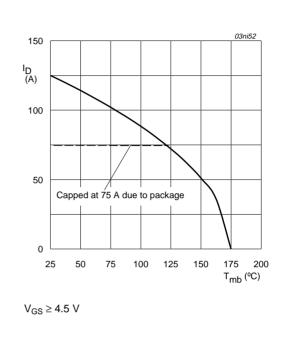
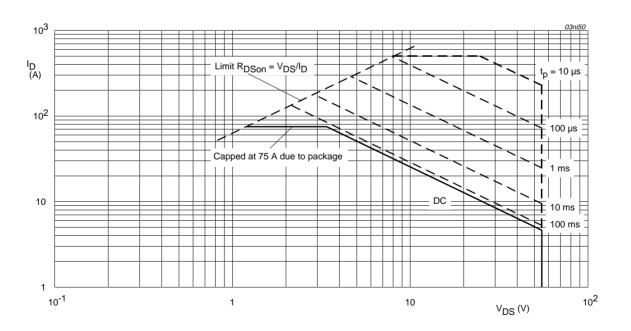


Fig 2. Continuous drain current as a function of mounting base temperature.



 $T_{mb}$  = 25 °C;  $I_{DM}$  single pulse.

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage.

#### 7. Thermal characteristics

Table 4: Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Figure 4	-	-	0.59	K/W	
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient						
	SOT78	vertical in still air	-	60	-	K/W	
	SOT404	mounted on a printed circuit board; minimum footprint	-	50	-	K/W	

### 7.1 Transient thermal impedance

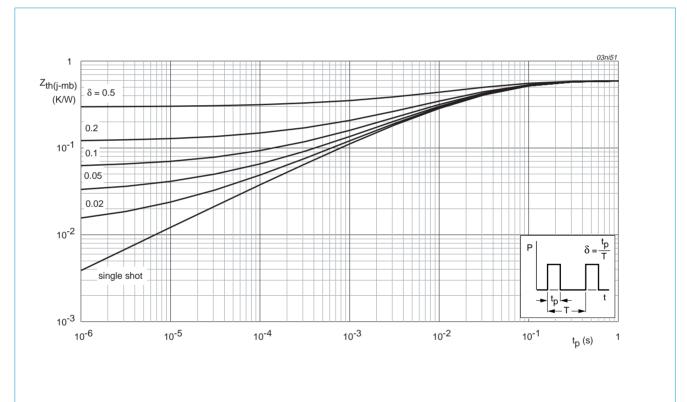


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration.

### 8. Characteristics

Table 5: Characteristics

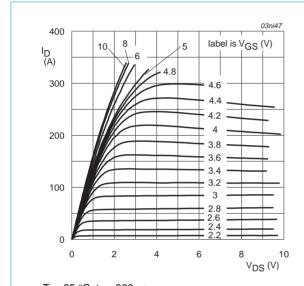
 $T_i = 25 \,^{\circ}C$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
V <sub>(BR)DSS</sub>	drain-source breakdown	I <sub>D</sub> = 0.25 mA; V <sub>GSf</sub> = 0 V				
	voltage	T <sub>j</sub> = 25 °C	55	-	-	V
		T <sub>j</sub> = −55 °C	50	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS};$ Figure 9				
		T <sub>i</sub> = 25 °C	1	1.5	2	V
		T <sub>i</sub> = 175 °C	0.5	-	-	V
		T <sub>i</sub> = −55 °C	-	-	2.3	V
I <sub>DSS</sub>	drain-source leakage current	V <sub>DS</sub> = 55 V; V <sub>GS</sub> = 0 V				
		T <sub>j</sub> = 25 °C	-	0.05	10	μΑ
		T <sub>i</sub> = 175 °C	-	-	500	μΑ
I <sub>GSS</sub>	gate-source leakage current	$V_{GS} = \pm 10 \text{ V}; V_{DS} = 0 \text{ V}$	-	2	100	nA
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS} = 5 \text{ V}; I_D = 25 \text{ A};$ Figure 7 and 8				
		T <sub>j</sub> = 25 °C	-	6.8	8	mΩ
		T <sub>j</sub> = 175 °C	-	-	16	mΩ
		V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 25 A	-	-	8.5	mΩ
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 25 A	-	6.4	7.5	mΩ
Dynamic	characteristics					
Q <sub>g(tot)</sub>	total gate charge	$V_{GS} = 5 \text{ V}; V_{DD} = 44 \text{ V};$	-	92	-	nC
$Q_{gs}$	gate-to-source charge	I <sub>D</sub> = 25 A; Figure 14	-	11	-	nC
$Q_{gd}$	gate-to-drain (Miller) charge		-	43	-	nC
C <sub>iss</sub>	input capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V};$	-	4551	6021	pF
C <sub>oss</sub>	output capacitance	f = 1 MHz; Figure 12	-	760	900	pF
C <sub>rss</sub>	reverse transfer capacitance		-	500	687	pF
t <sub>d(on)</sub>	turn-on delay time	$V_{DD} = 30 \text{ V}; R_L = 1.2 \Omega;$	-	40	-	ns
t <sub>r</sub>	rise time	$V_{GS} = 5 \text{ V}; R_G = 10 \Omega$	-	175	-	ns
t <sub>d(off)</sub>	turn-off delay time		-	280	-	ns
t <sub>f</sub>	fall time		-	167	-	ns
L <sub>d</sub>	internal drain inductance	from drain lead 6 mm from package to centre of die	-	4.5	-	nΗ
		from contact screw on mounting base to centre of die SOT78	-	3.5	-	nH
		from upper edge of drain mounting base to centre of die SOT404	-	2.5	-	nH
L <sub>s</sub>	internal source inductance	from source lead to source bond pad	-	7.5	-	nΗ

**Product data sheet** 

**Table 5:** Characteristics...continued  $T_i = 25 \,^{\circ}$ C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Source-di	rain diode					
$V_{SD}$	source-drain (diode forward) voltage	$I_S = 25 \text{ A}; V_{GS} = 0 \text{ V};$ Figure 15	-	0.85	1.2	V
t <sub>rr</sub>	reverse recovery time	$I_S = 75 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s}$	-	70	-	ns
Q <sub>r</sub>	recovered charge	$V_{GS} = -10 \text{ V}; V_{DS} = 25 \text{ V}$	-	170	-	nC



 $T_j = 25 \, ^{\circ}\text{C}; \, t_p = 300 \, \mu\text{s}$ 

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values.

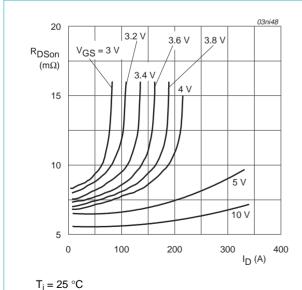
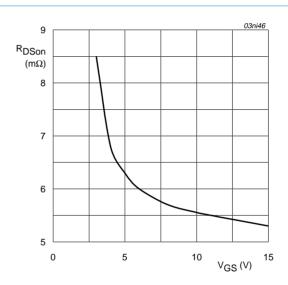
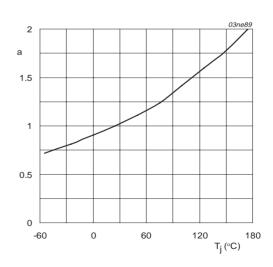


Fig 7. Drain-source on-state resistance as a function of drain current; typical values.



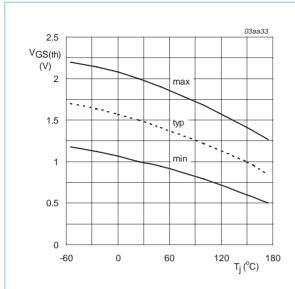
 $T_{j} = 25 \,^{\circ}\text{C}; I_{D} = 25 \,^{\circ}\text{A}$ 

Fig 6. Drain-source on-state resistance as a function of gate-source voltage; typical values.



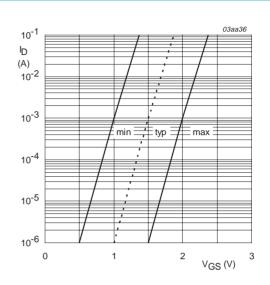
 $a = R_{DSon}/R_{DSon(25 °C)}$ 

Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature.



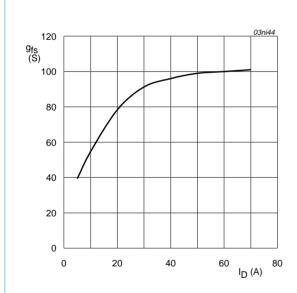
 $I_D = 1 \text{ mA}; V_{DS} = V_{GS}$ 

Fig 9. Gate-source threshold voltage as a function of junction temperature.



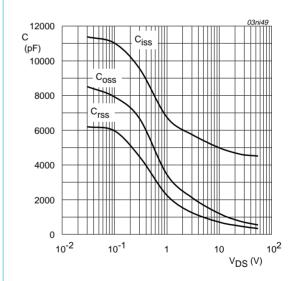
$$T_j = 25 \,^{\circ}C; V_{DS} = V_{GS}$$

Fig 10. Sub-threshold drain current as a function of gate-source voltage.



 $T_i = 25 \,^{\circ}C; V_{DS} = 25 \,^{\circ}V$ 

Fig 11. Forward transconductance as a function of drain current; typical values.



 $V_{GS} = 0 V; f = 1 MHz$ 

Fig 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values.

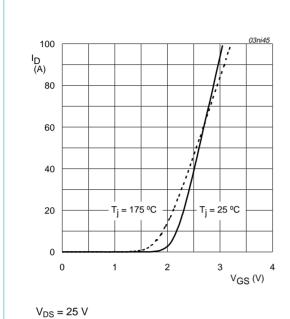
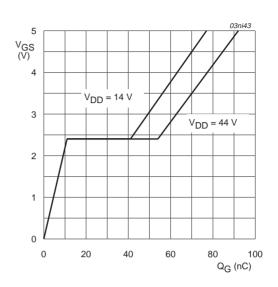
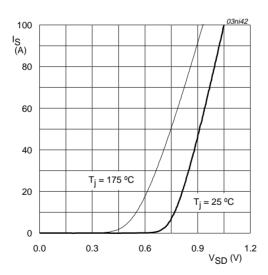


Fig 13. Transfer characteristics: drain current as a function of gate-source voltage; typical values.



 $T_i = 25 \,^{\circ}C; I_D = 25 \,^{\circ}A$ 

Fig 14. Gate-source voltage as a function of turn-on gate charge; typical values.



 $V_{GS} = 0 V$ 

Fig 15. Reverse diode current as a function of reverse diode voltage; typical values.

### 9. Package outline

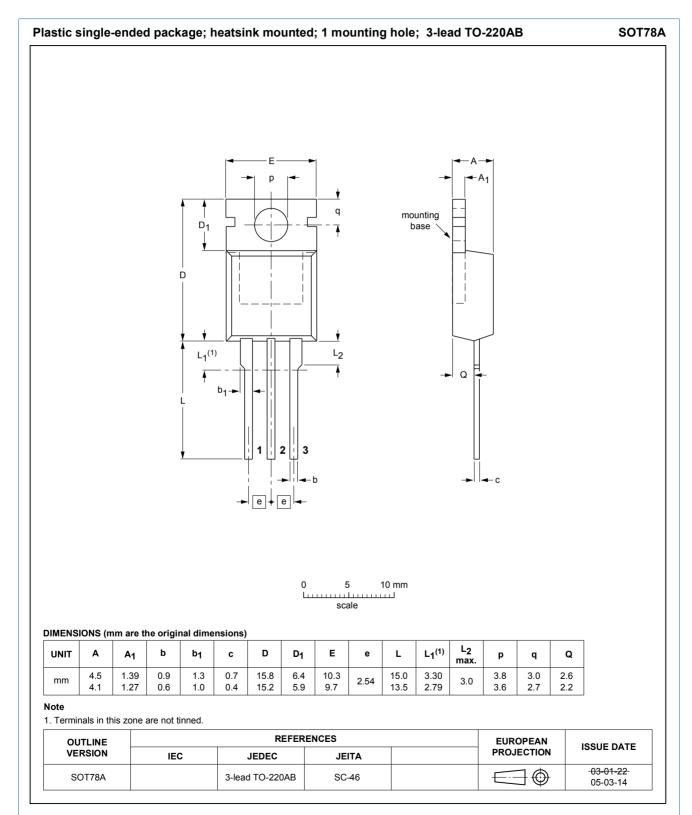


Fig. 16. Package outline TO-220AB (SOT78A)

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# **BUK9508-55A**

#### **Nexperia**

TrenchMOS™ logic level FET

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